



Dual N-Channel 40-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---------------------|----------------------------------|---------------------------------|-----------------------|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^a | Q _g (Typ.) | |
| 40 | 0.027 at V _{GS} = 10 V | 6.0 | 9.6 | |
| | 0.032 at V _{GS} = 4.5 V | 4.8 | 9.0 | |

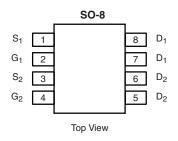
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested

Pb-free ROHS COMPLIANT HALOGEN FREE Available

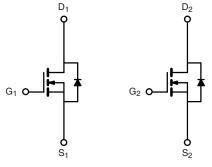
APPLICATIONS

CCFL Inverter



Ordering Information: Si4910DY-T1-E3 (Lead (Pb)-free)

Si4910DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS $T_A =$ | 25 °C, unless other | wise noted | | | |
|-----------------------------------------------------|-------------------------------------|--------------------|----------------------|---|--|
| Parameter | Symbol | Limit | Unit | | |
| Drain-Source Voltage | | V_{DS} | 40 | V | |
| Gate-Source Voltage | V_{GS} | ± 16 |] | | |
| | T _C = 25 °C | | 7.6 | | |
| Continuous Drain Current (T _{.1} = 150 °C) | T _C = 70 °C | - I _D | 6.0 | [| |
| Continuous Brain Current (1) = 130 °C) | T _A = 25 °C | | 6.0 ^{b, c} | [| |
| | T _A = 70 °C | | 4.8 ^{b, c} | | |
| Pulsed Drain Current (10 μs Pulse Width) | | I _{DM} | 20 | A | |
| Source-Drain Current Diode Current | T _C = 25 °C | . I _S | 2.6 | | |
| Source-Drain Current blode Current | T _A = 25 °C | 'S | 1.6 ^{b, c} | [| |
| Pulsed Source-Drain Current | | I _{SM} | 20 | | |
| Single Pulse Avalanche Current | | I _{AS} 10 | | | |
| Single Pulse Avalanche Energy | e Pulse Avalanche Energy L = 0.1 mH | | 5 | | |
| | T _C = 25 °C | | 3.1 |] | |
| Maximum Power Dissipation | T _C = 70 °C | P_{D} | 2 | W | |
| Maximum Fower Dissipation | T _A = 25 °C | ' D | 2 ^{b, c} | | |
| | T _A = 70 °C | | 1.28 ^{b, c} | Ī | |
| Operating Junction and Storage Temperature Range | T _J , T _{stg} | - 55 to 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|---------------------------------------------|--------------|-------------------|------|------|------|--|
| Parameter | Symbol | Тур. | Max. | Unit | | |
| Maximum Junction-to-Ambient ^{b, d} | t ≤ 10 s | R _{thJA} | 49 | 62.5 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady-State | R _{thJF} | 30 | 40 | | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under steady state conditions is 120 °C/W.

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| SPECIFICATIONS $T_J = 25 ^{\circ}C$, | | | N.A.: | - 2 | | , |
|-----------------------------------------------|----------------------------------|----------------------------------------------------------------------------|-------|-------------------|-------|---------|
| Parameter | Symbol | Test Conditions | Min. | Typ. ^a | Max. | Unit |
| Static Static Notice Parallel and Mallace | l v | V 0.V I 050 A | 40 | | I | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 40 | | | V |
| V _{DS} Temperature Coefficient | ΔV _{DS} /T _J | In = 250 uA | | 37 | | mV/°C |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | | | - 5 | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 0.6 | | 2.0 | V |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$ | | | 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 40 V, V _{GS} = 0 V | | | 1 | μΑ |
| | 500 | $V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$ | | | 10 | |
| On-State Drain Current ^b | I _{D(on)} | $V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 20 | | | Α |
| Drain Source On State Besistance | R _{DS(on)} | $V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$ | | 0.022 | 0.027 | Ω |
| Drain-Source On-State Resistance ^b | 1 10S(on) | $V_{GS} = 4.5 \text{ V}, I_D = 4.8 \text{ A}$ | | 0.026 | 0.032 | |
| Forward Transconductance ^b | 9 _{fs} | $V_{DS} = 15 \text{ V}, I_{D} = 6 \text{ A}$ | | 20 | | S |
| Dynamic ^a | | | | | | |
| Input Capacitance | C _{iss} | | | 855 | | |
| Output Capacitance | C _{oss} | $V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, I_D = 1 \text{ MHz}$ | | 105 | | pF |
| Reverse Transfer Capacitance | C _{rss} | 1 | | 65 | | |
| Total Oata Obania | 0 | $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$ | | 21 | 32 | nC |
| Total Gate Charge | Q _g | | | 9.6 | 14.5 | |
| Gate-Source Charge | Q _{gs} | $V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$ | | 2.3 | | |
| Gate-Drain Charge | Q_{gd} | | | 3.2 | | |
| Gate Resistance | R_{g} | f = 1 MHz | | 2.5 | 3.8 | Ω |
| Turn-On Delay Time | t _{d(on)} | | | 6 | 12 | |
| Rise Time | t _r | $V_{DD} = 20 \text{ V}, R_L = 4 \Omega$ | | 11 | 20 | 1 |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | | 24 | 36 | |
| Fall Time | t _f | 1 | | 6 | 12 | 1 |
| Turn-On Delay Time | t _{d(on)} | | | 12 | 20 | ns - |
| Rise Time | t _r | $V_{DD} = 20 \text{ V}, R_1 = 4 \Omega$ | | 60 | 90 | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | | 22 | 33 | |
| Fall Time | t _f | j | | 5 | 10 | 1 |
| Drain-Source Body Diode Characteristi | cs | | | <u> </u> | | |
| Continuous Source-Drain Diode Current | I _S | T _C = 25 °C | | | 2.6 | |
| Pulse Diode Forward Current ^a | I _{SM} | | | | 20 | A |
| Body Diode Voltage | V _{SD} | I _S = 1.5 A | | 0.73 | 1.2 | V |
| Body Diode Reverse Recovery Time | t _{rr} | - | | 26 | 40 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | 1 | | 21 | 32 | nC |
| Reverse Recovery Fall Time | t _a | $I_F = 5$ A, dl/dt = 100 A/μs, $T_J = 25$ °C | | 13 | | ns |
| Reverse Recovery Rise Time | t _b | | | 13 | | |

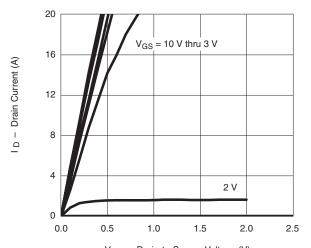
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



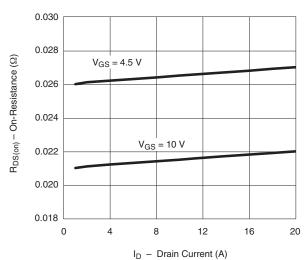


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

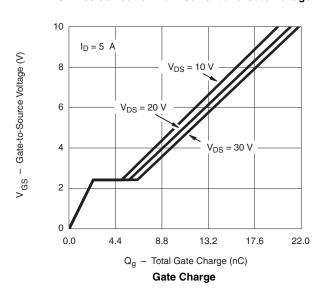


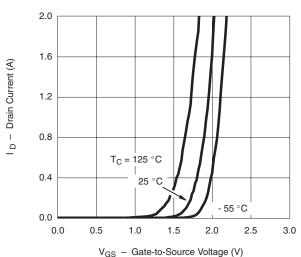
V_{DS} - Drain-to-Source Voltage (V)



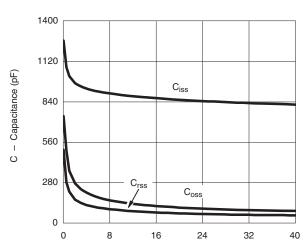


On-Resistance vs. Drain Current and Gate Voltage



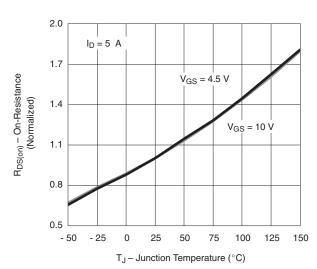






V_{DS} - Drain-to-Source Voltage (V)

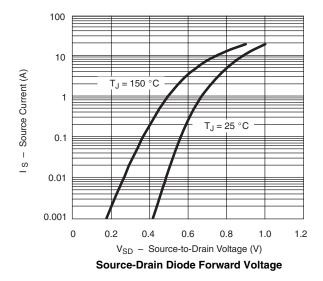
Capacitance

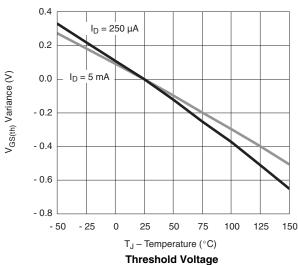


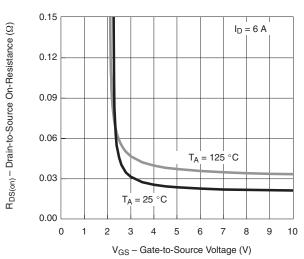
On-Resistance vs. Junction Temperature

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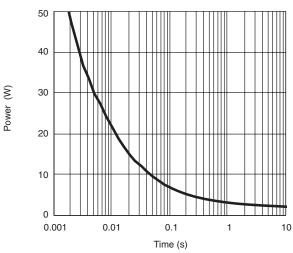
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



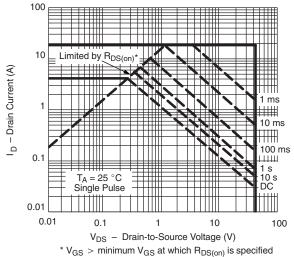




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

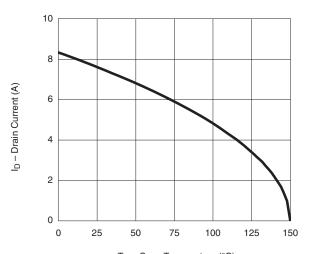


Safe Operating Area, Junction-to-Ambient



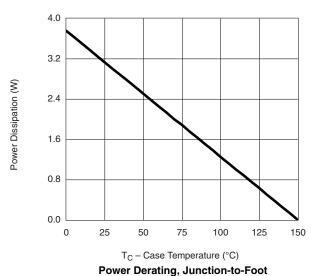


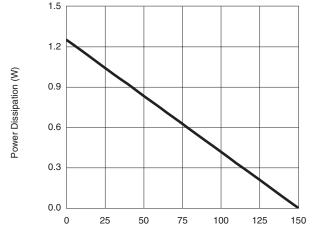
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 T_C – Case Temperature (°C)

Current Derating*





T_A – Ambient Temperature (°C)

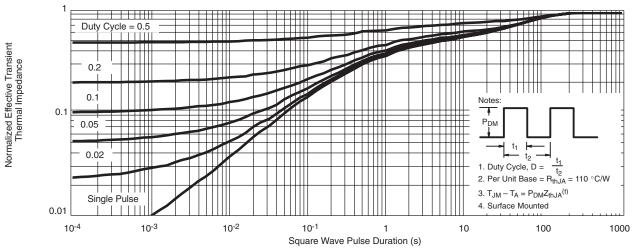
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

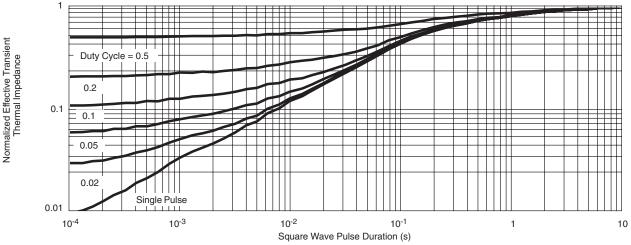
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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